APPLIED
MATERIALS®
make possible

Multimedia Available: Chipmakers Break Low k Barrier, Take Leap Forward to Drive Next-Generation Electronics Using Applied Black Diamond

February 5, 2004

--(BUSINESS WIRE)--

Key semiconductor designers, manufacturers and Applied Materials Inc. today mark the beginning of the Low k Era in chipmaking. Semiconductor companies Agere Systems, Altera Corp., AMD, ATI Technologies, LSI Logic, NEC and Toshiba, and semiconductor foundry TSMC, are utilizing Applied Materials' Black Diamond(R) low k film to manufacture some of the world's most advanced chips.

You can reach the story directly by going to http://www.newstream.com/cgi-bin/display_story.cgi?12197

This multimedia news story is for free and unrestricted use on your news information site (and for print or broadcast too). Visit http://www.newstream.com to download video, audio, text, graphics and photos.

If you have any questions about the story, or about Newstream.com, please write to us at info@newstream.com.

CONTACT: Newstream
info@newstream.com

SOURCE: Newstream and Applied Materials Inc.